AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A surface protecting adhesive film for a semiconductor wafer ~~in which an adhesive layer is~~ comprising:

a base film which comprises at least one layer of a synthetic resin wherein the base film has a storage elastic modulus (E') of at 25°C of from $1x10^3$ to $1x10^{10}$ Pa and wherein the base film has a thickness of 10 μm to 120 μm; and

an adhesive layer of 5 to 50 μm in thickness formed on one surface of [[a]] the base film, wherein the adhesive layer comprises 100 weight parts of a polymer (A) having a functional group capable of reacting with a cross-linking agent and a temperature (Ta) in a range of from -50°C to 5°C at which tan δ of a dynamic viscoelasticity of the polymer(A) is maximized , from 10 weight parts to 100 weight parts of a polymer (B) having a functional group capable of reacting with a cross-linking agent and a temperature (Tb) in a range of from more than 5°C to 50°C at which tan δ of a dynamic viscoelasticity of the polymer(B) is maximized , and from 0.1 weight part to 10 weight parts of a cross-linking agent (C) having two or more cross-linkable functional groups in a molecule based on 100 weight parts of total amount of the polymers (A) and (B)~~, wherein the thickness of the adhesive layer is from 5 μm to 50 μm~~.

2. - 4. (Canceled)

5. (Previously Presented) The surface protecting adhesive film for the semiconductor wafer according to claim 1, wherein polymers (A) and (B) are acrylic acid alkyl ester copolymers.

6. (Withdrawn) A protecting method for a semiconductor wafer comprising the steps of: applying a surface protecting adhesive film for the semiconductor wafer on a circuit-forming surface of the semiconductor wafer via an adhesive layer thereof; grinding a non-circuit-formed surface of the semiconductor wafer; and peeling away the surface protecting adhesive film for the semiconductor wafer , wherein the surface protecting adhesive film for the semiconductor wafer according to claim 5 is used in the protecting method for the semiconductor wafer.

7. (Canceled)

8. (Withdrawn) A protecting method for a semiconductor wafer comprising the steps of: applying a surface protecting adhesive film for the semiconductor wafer on a circuit-forming surface of the semiconductor wafer via an adhesive layer thereof; grinding a non-circuit-formed surface of the semiconductor wafer; and peeling away the surface protecting adhesive film for the semiconductor wafer , wherein the surface protecting adhesive film for the semiconductor wafer according to claim 1 is used in the protecting method for the semiconductor wafer.